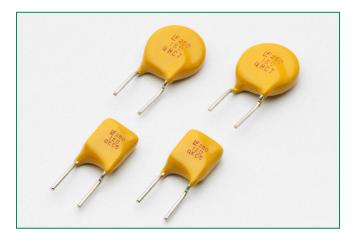
250R Series Radial Leaded



Additional Information







Resources

Agency Approvals

Agency	Agency File Number
c 🔊 us	E183209
${\bf \Delta}$	R50120008

Description

The 250R Series is designed to protect against short duration high voltage fault currents (power cross or power induction surge) typically found in telecom applications (250Vrms). The series can be used to help telecom networking equipment meet the protection requirements specified in ITU K.20 and K.21.

Features

- 0.08 0.18 hold current range, 60VDC operating voltage
- 250VAC interrupt rating
- Fast time-to-trip

Applications

- Customer Premises Equipment (CPE)
- Central Office (CO)/ telecom centers

- Binned and sorted narrow resistance ranges available
- RoHS-compliant, Lead-Free and Halogen-Free*
- LAN/WAN equipment
- Access equipment

Electrical Characteristics

Part Number	Number I hold I trip V max I max P Maximum Time To Ti		Time To Trip	p Resistance			Agency Approvals					
Part Number	(A)	(Å)	V_{int}/V_{op}	(Å) typ. (W)	Current (A)	Time (Sec.)	R _{min} (Ω)	$\mathbf{R}_{typ}(\Omega)$	R _{1max} (Ω)	c AL us	\triangle	
250R080	0.08	0.16	250/60	3	1	0.35	4.0	14	22	33	Х	Х
250R120	0.12	0.24	250/60	3	1	1	2.5	4	8	16	Х	Х
250R120-RA	0.12	0.24	250/60	3	1	1	2.5	7	9	16	Х	Х
250R120-RC	0.12	0.24	250/60	3	1	1	3.0	5.4	7.5	14	Х	Х
250R120-R2	0.12	0.24	250/60	3	1	1	2.5	8	10.5	16	Х	Х
250R145	0.145	0.29	250/60	3	1	1	2.5	3	6	14	Х	Х
250R180	0.18	0.65	250/60	10	1.8	1	20	0.8	2.2	4	Х	Х

Note: Items with T at end of part number = pre-tripped device. See Part Ordering Number System section of this data sheet for additional information.

I hold = Hold current: maximum current device will pass without tripping in 20°C still air.

= Maximum fault current device can withstand without damage at rated voltage (Vmay

 \mathbf{P}_{d} = Power dissipated from device when in the tripped state at 20°C still air.

R min = Minimum resistance of device in initial (un-soldered) state. typ = Typical resistance of device in initial (un-soldered) state.

R tmax = Maximum resistance of device at 20°C measured one hour after tripping.

* Effective February 11, 2010 onward, all 600R PTC products will be manufactured Halogen Free (HF). Existing Non-Halogen Free 600R PTC products may continue to be sold, until supplies are depleted. This change will have no effect on 600R product specifications or performance.

Warning

· Users shall independently assess the suitability of these devices for each of their applications

• Operation of these devices beyond the stated maximum ratings could result in damage to the devices and lead to electrical arcing and/or fire

• These devices are intended to protect against the effects of temporary over-current or over-temperature conditions and are not intended to perform as protective devices where such conditions are expected to be repetitive or prolonged in duration

- Exposure to silicon-based oils, solvents, electrolytes, acids, and similar materials can adversely affect the performance of these PPTC devices
- These devices undergo thermal expansion under fault conditions, and thus shall be provided with adequate space and be protected against mechanical stresses

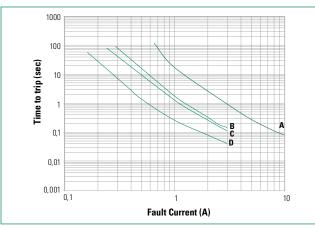
• Circuits with inductance may generate a voltage (L di/dt) above the rated voltage of the PPTC device.



1

Temperature Rerating

Ambient Operation Temperature									
	-40°C	-20°C	0°C	20°C	40°C	50°C	60°C	70°C	85°C
Part Number	Hold Current (A)								
250R080	0.12	0.11	0.09	0.08	0.06	0.05	0.05	0.04	0.03
250R120	0.18	0.16	0.14	0.12	0.10	0.09	0.08	0.06	0.05
250R145	0.26	0.20	0.17	0.145	0.12	0.11	0.09	0.08	0.06
250R180	0.28	0.23	0.21	0.18	0.16	0.13	0.10	0.11	0.083

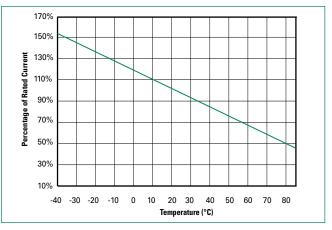


Average Time Current Curves

The average time current curves and Temperature Rerating curve performance is affected by a number or variables, and these curves provided as guidance only. Customer must verify the performance in their application.

Curve Designation	I _{hold} (A)
А	0.18
В	0.145
С	0.12
D	0.80

Temperature Rerating Curve



 $[\]ensuremath{\textbf{Note:}}$ Typical Temperature rerating curve, refer to table for derating data

Agency Specification Selection Guide For Telecom and Networking Applications

Product	Lightning	Power Cross
250R120 250R145	ITU K.20/21/45 – 1.5kV 10/700μs ITU K.20/21/45 – 4kV 10/700μs*	ITU K.20/21/45 – 230Vac, 10Ω ITU K.20/21/45 – 600Vac, 600Ω
250R180	ITU K.20/21/45 – 1.5kV 10/700μs ITU K.20/21/45 – 4kV 10/700μs* Telcordia GR – 974 – 1.0kV 10/1000μs	ITU K.20/21/45 – 230Vac, 10Ω ITU K.20/21/45 – 600Vac, 600Ω Telcordia GR – 974- 283Vac, 10A

*Devices should be independently evaluated and tested for use in any specific application

Protection Application Guide

Region/Specification	Application	Device Selection
South America/Asia/Europe ITU K.45	*Access network equipment, Remote terminal Repeaters, WAN equipment, Cross –connect	250R180 250R145 250R120
South America/Asia/Europe ITU K.21	Customer and IT equipment, Analog modems ADSL, xDSL, Phone sets, PBX systems, Internet appliances, POS terminals	250R180 250R145 250R120
South America/Asia/Europe ITU K.20	Central Office, POTS/ISDN linecards, T1/E1/J1 linecards, ADSL/VDSL splitters, CSU/DSU,	250R180 250R145 250R120
North America Telcordia GR-974	*Primary protection modules,	250R180
South America/Asia/Europe ITU K.20	MDF modules, Network interface	250R145 250R120
North America Telcordia GR-1089		250R180
South America/Asia/Europe ITU K.20 and K.21	*Intrabuilding communication systems, LAN, VOIP cards, Local loop handsets,	250R145 250R120
-	LAN Intrabuilding power cross, Protection, LAN equipment, IP phone	250R080

*Resistance binned parts are recommended

Soldering Parameters - Wave Soldering

Condition	Wave Soldering
Peak Temp/ Duration Time	260°C ≦ 5 Sec
≧ 220°C	2 Sec ~ 20 Sec
Preheat 140°C~ 180°C	180 Sec ~ 210 Sec
Storage Condition	0°C~35°C, ≦ 70%RH

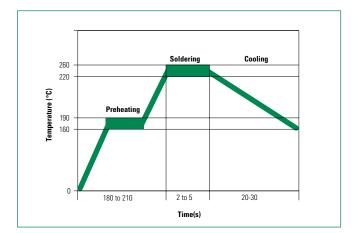
Note:

Recommended soldering methods: heat element oven or N₂ environment for lead–free
 Devices are designed to be wave soldered to the bottom side of the board.

Devices are designed to be wave soldered to the bottom side of the board.
Devices can be cleaned using standard industry methods and solvents.

Devices can be cleaned using standard industry methods
This profile can be used for lead-free device

 If soldering temperatures exceed the recommended profile, devices may not meet the performance requirements.



Resettable PPTC Datasheet

Physical Specifications

Lead Material	Tin-plated Copper
Soldering Characteristics	Solderability per MIL–STD–202, Method 208
Insulating Material	Cured, flame retardant epoxy polymer meets UL94V-0 requirements.
Device Labeling	Marked with 'LF', voltage, current rating, and date code.

Environmental Specifications

Operating Temperature	-40°C to +85°C
Maximum Device Surface Temperature in Tripped State	125°C
Passive Aging	65°C/85°C, 1000 hours
Humidity Aging	+85°C, 85% R.H,.1000 hours
Thermal Shock	MIL–STD–202, Method 107 +125°C to -55°C 10 times
Solvent Resistance	MIL-STD-202, Method 215
Moisture Sesitivity Level	Level 1, J-STD-020

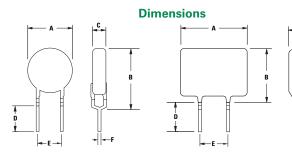
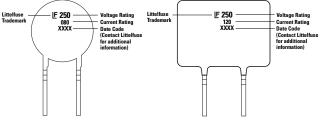


Figure 2

Part Marking System



С D **Physical Characteristics** Α в E Part Number Figure Inches mm Inches mm Inches mm Inches mm Inches mm Lead (dia) Material Inches Max. Max. Max. Max Max. Max Min. Min. Тур. Тур. mm 250R080 1 0.23 5.8 0.39 9.9 0.18 4.6 0.19 4.7 0.20 5.1 0.026 0.65 Sn/Cu 0.65 250R120 2 0.27 6.8 0.43 11 0.18 4.6 0.19 4.7 0.20 5.1 0.026 Sn/Cu 2 250R120-RA 0.27 6.8 0.43 0.18 4.6 0.19 4.7 0.20 5.1 0.026 0.65 Sn/Cu 11 250R120-RC 2 0.27 6.8 0.43 11 0.18 4.6 0.19 4.7 0.20 5.1 0.026 0.65 Sn/Cu 0.27 250R120-R2 2 6.8 0.43 11 0.18 4.6 0.19 4.7 0.20 5.1 0.026 0.65 Sn/Cu 0.27 6.8 0.20 0.026 0.65 250R145 2 0.43 11 0.18 4.6 0.19 4.7 5.1 Sn/Cu 250R180 0.47 0.20 1 0.37 9.5 12 0.18 4.6 0.19 4.7 5.1 0.026 0.65 Sn/Cu

WARNING:

Figure 1

• Users shall independently assess the suitability of these devices for each of their applications

Operation of these devices beyond the stated maximum ratings could result in damage to the devices and lead to electrical arcing and/or fire
 These devices are intended to protect against the effects of temporary over-current or over-temperature conditions and are not intended to perform as protective devices where such conditions are expected to be

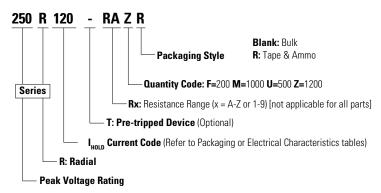
repetitive or prolonged in duration

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· Circuits with inductance may generate a voltage (L di/dt) above the rated voltage of the PPTC device

Part Ordering Number System





Resettable PPTC Datasheet

	kaging
Pac	vadind

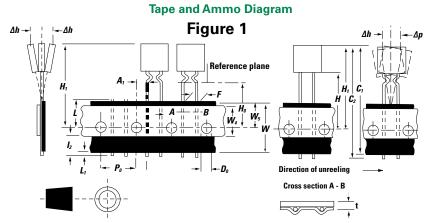
Part Number	Ordering Number	I _{hold} (A)	I _{hold} Code	Packaging Option	Quantity	Quantity & Packaging Codes	
250R080	250R080U	0.080	080	Bulk	500	U	
200000	250R080ZR	0.060	060	Tape and Ammo	1200	ZR	
250R120	250R120U	0.120	120	Bulk	500	U	
2506120	250R120ZR	0.120	120	Tape and Ammo	1200	ZR	
250R120-RA	250R120-RAZR	0.120	120	Tape and Ammo	1200	ZR	
250R120-RC	250R120-RCZR	0.120	120	Tape and Ammo	1200	ZR	
250R120-R2	250R120-R2ZR	0.120	120	Tape and Ammo	1200	ZR	
250R145	250R145ZR	0.145	145	Tape and Ammo	1200	ZR	
250R180	250R180F	0.180	180	Bulk	200	F	
2006180	250R180MR	0.180	180	Tape and Ammo	1000	MR	

Tape and Ammo Specifications

Devices taped using EIA468-B/IE286-2 standards. See table below and Figure 1 for details.

Dimension			Dimen	sions
Dimension	EIA Mark	IEC Mark	Dim. (mm)	Tol. (mm)
Carrier tape width	W	W	18	-0.5 / +1.0
Hold down tape width	W4	Wo	11	min.
Top distance between tape edges	W ₆	W ₂	3	max.
Sprocket hole position	W ₅	W 1	9	-0.5 / +0.75
Sprocket hole diameter*	D	Do	4	-0.32 / +0.2
Abscissa to plane (straight lead)	Н	Н	18.5	-/+ 3.0
Abscissa to plane (kinked lead)	Ho	Ho	16	-/+ 0.5
Abscissa to top	H ₁	H ₁	32.2	max.
Overall width without lead protrusion	C 1	-	42.5	max.
Overall width with lead protrusion	C ₂	-	43.2	max.
Lead protrusion	L ₁	I1	1.0	max.
Protrusion of cut out	L	L	11	max.
Protrusion beyond hold–down tape	l ₂	1 2	Not specified	-
Sprocket hole pitch: 250R080– 250R145	Po	Po	12.7	-/+ 0.3
Sprocket hole pitch: 250R180	Po	Po	25.4	-/+ 0.5
Pitch tolerance	-	-	20 consecutive.	-/+ 1
Device pitch: 250R080-250R145	-	-	12.7	-
Device pitch: 250R180	-	-	25.4	-
Tape thickness	t	t	0.9	max.
Tape thickness with splice	t ₁	-	2.0	max.
Splice sprocket hole alignment	-	-	0	-/+ 0.3
Body lateral deviation	Δh	Δh	0	-/+ 1.0
Body tape plane deviation	Δp	Δр	0	-/+ 1.3
Ordinate to adjacent component lead*	P ₁	P ₁	3.81	-/+ 0.7
Lead spacing	F	F	5.1	-/+ 0.7

*Differs from EIA Specification



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